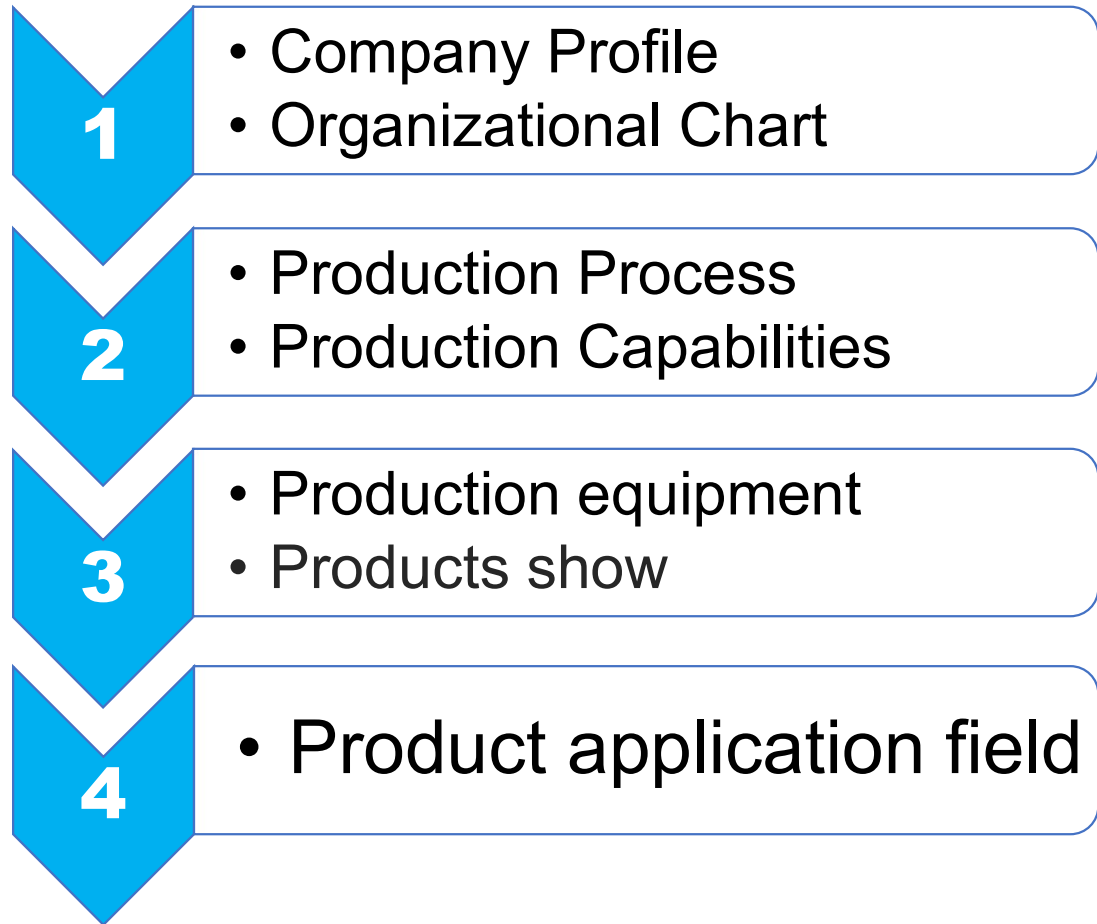


惠州市信达源科技有限公司
HUIZHOU XINDAYUAN TECHNOLOGY CO.,LTD



Company Profile

CONTENTS





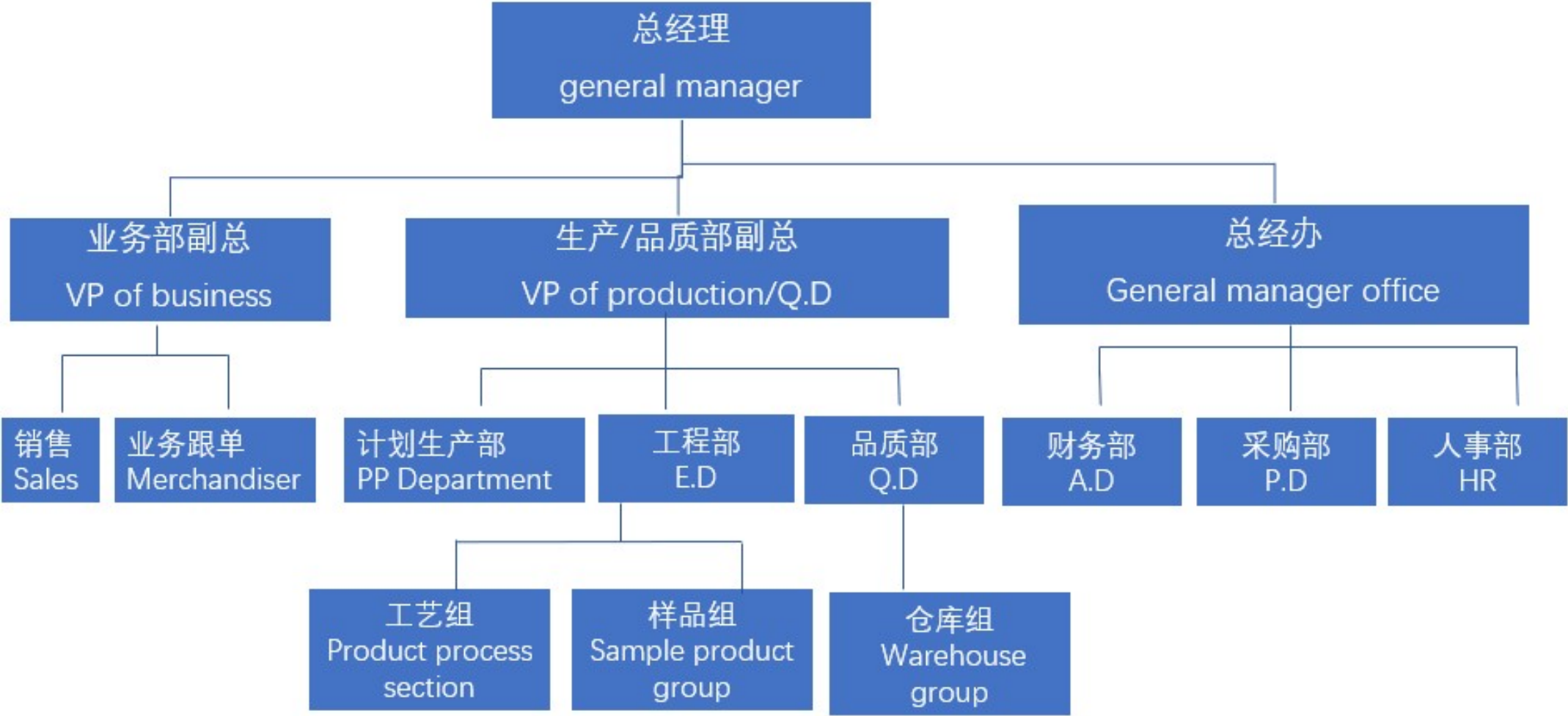
Manufacturing FPC/PCB for 16 years

Xindayuan(Threetek group) has accumulated more than 16 years professional manufacturing FPC/PCB experience,aderring to " quality,integrity,inovation,feedback" the business philosophy for the electronics industry to provide nearly thousand different specifications of the FPC/PCB products. We focusing on high-tech FPC/Rigid-flex in hi-mixed, quick-turn prototype, small/medium volume. Applied into telecommunication, industrial control, security surveillance, healthcare, automotive etc.

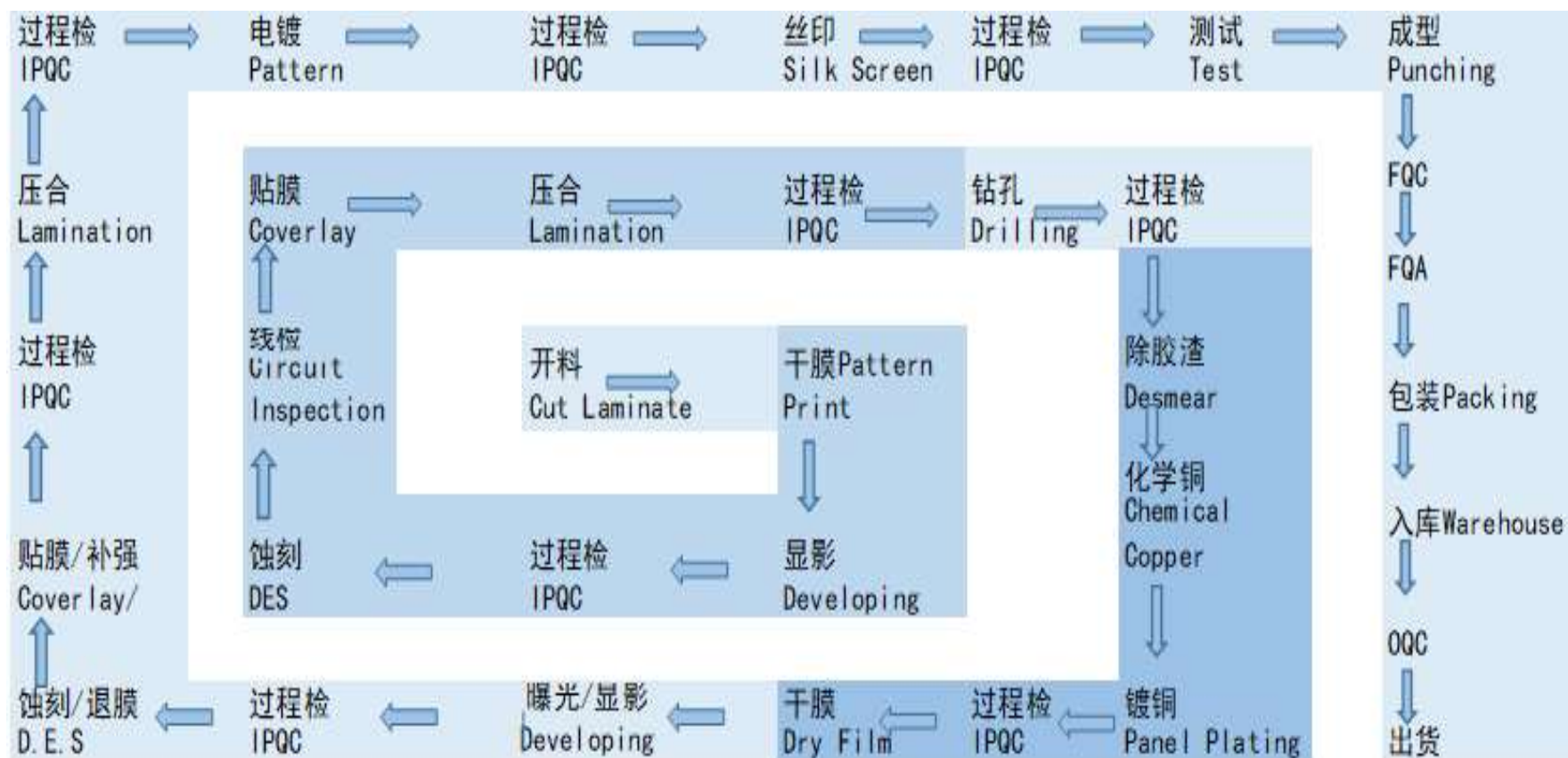
25000sqm factory with 300 Employees

Our 25000sqm production base has obtained UL, ISO9001:2015, IATF16949:2016, ISO14001:2016 certification with convenient transportation. We employ more than 300 skilled factory workers including 50 engineers and technicians to

Organizational Chart



Production Process



Production Capabilities

序号No.	流程 Technological process	详述Detailed	量产能力Production capacity	样品及小批量能力Sample and small batch capacity
1	材料(Material)	材料厚度公差(Material thickness tolerance)	如无特别说明(If not specified): ±10%	如无特别说明(If not specified): ±10%
2	层数(layers)	软板(FPC)	1-6layers	1-8layers
		软硬板(Rigid-Flex)	2-6layers	2-8layers
3	尺寸(size)	最小产品尺寸(Minimum product size)	3*15mm	2*10mm
		最大产品尺寸长度 (Maximum product size)	≤600mm	≤700mm
4	开料(Material cutting)	补强类开料精度(Cutting precision)	±0.2mm	±0.1mm

Production Capabilities

5	钻孔(Drilling)	钻孔孔径公差(Aperture tolerance)	±0.05mm	±0.025mm
		钻孔位置公差(Hole position tolerance)	±0.05mm	±0.05mm
		钻孔最小间距(孔边到边)(Minimum drilling distance(hole edge to hole edge))	≥0.20 mm	≥0.10 mm
		内层孔到其它网络导体距离(The distance between the inner hole and other network conductor)	≥0.20 mm	≥0.15 mm
		最小激光钻孔(Minimum laser drilling)	0.1mm	0.075mm
		钻咀尺寸(Nozzle size)	0.2mm~6.5mm	0.15mm~6.5mm
6	沉铜/板镀 (copper deposition/copper plating)	孔径纵横比（板厚比孔径，软硬结合板类） Aperture aspect ratio(thickness ratio aperture)	5:1	6:1
		最小孔径(Minimum aperture)	≥0.1mm	≥0.075mm
		最大孔铜厚(Maximum thickness for hole copper)	35um	50um
		最小孔铜厚(Minimum thickness for hole copper)	≥10um	≥10um
7	清洁(clean)	最小磨板厚度(Minimum thickness of Polishing FPC)	≥0.05mm	≥0.05mm
		最小洗板厚度(Minimum thickness of cleaning FPC)	≥0.05mm	≥0.05mm
8	层压 (Laminate)	层间对位偏差(Deviation between layers)	±0.075mm	±0.05mm

Production Capabilities

9	蚀刻(Etching)	最小线宽/线距控制(Minimum line width/space control)	完成铜厚Complete copper thickness:12-18um W/S: 2.5/2.5mil	完成铜厚Complete copper thickness:18um W/S: 2.0/2.0mil
			完成铜厚18-35um W/S: 4/4mil	完成铜厚35um W/S: 3/3mil
			完成铜厚35-50um W/S: 5/5mil	完成铜厚50um W/S: 4/4mil
			完成铜厚50-70um W/S: 7/7mil	完成铜厚70um W/S: 6/6mil
		线宽线距公差(Tolerances for width and spacing)	±0.02mm (线宽线距 ≥0.3mm±10%)	±0.015mm (线宽线距 ≥0.2mm±10%)
		手指Pitch公差 (首尾两PIN) (Finger Pitch tolerance)	0≤Pitch≤30mm ±0.05mm 30<Pitch≤50mm±0.08mm 50<Pitch≤100mm ±0.12mm	0≤Pitch≤30mm ±0.05mm 30<Pitch≤50mm±0.08mm 50<Pitch≤100mm ±0.12mm
		双面板过孔PAD最小孔环(Minimum ring of through hole)	≥0.075mm	≥0.075mm
		导体离外形或NPTH最小距离(The minimum distance between the conductor and the outline or NPTH)	≥0.15mm	≥0.10mm
		多层板内层过孔PAD最小孔环(The innermost layer of the multilayer FPC, the smallest hole PAD ring)	≥0.1mm	≥0.1mm
10	冲孔Punching hole	标准工具孔尺寸(Standard tool hole dimensions)	2.0mm	2.0mm or 3.0mm
		工具孔位置公差(Tool hole position tolerance)	±0.025mm	±0.025mm
		工具孔大小公差 (Tool hole size tolerance)	±0.025mm	±0.025mm
		工具孔心到板边最小距离(The minimum distance from the center of the tool hole to the edge of the outline)	≥5mm	≥4mm

Production Capabilities

11	贴合(Fit)	覆盖膜累计公差（包括偏位、溢胶、尺寸公差等）(Cumulative tolerance of covering film (including deflection, overflow, size tolerance, etc.))	±0.20mm	±0.15mm
		最大溢胶量(Maximum overflow)	≤0.15mm	≤0.08mm
		覆盖膜不上PAD的最小距离(The minimum distance between the covering film and PAD)	≥0.12mm	≥0.1mm
		覆盖膜不露线或铜的最小距离(The minimum distance of the covering film to a line or copper)	≥0.1mm	≥0.1mm
		最小覆盖膜桥宽(Minimum covering membrane width)	≥0.5mm	≥0.3mm
		保护膜最小方形开窗(Minimum square window with covering film)	0.5*0.5mm	0.5*0.5mm(开精密模或激光)
		覆盖膜开窗与外形边距离公差(Covering film opening to edge tolerance)	±0.20mm	±0.15mm
12	板厚(FPC thickness)	FPC最小板厚(FPC minimum thickness)	0.07+/-0.03mm	0.05+/-0.02mm
13	表面处理(Surface treatment)	OSP	有机保护膜（抗氧化处理）	
		有铅喷锡（HASL）,仅对应软硬结合板外发	Sn: 2um-40um	Sn: 2um-40um
		无铅喷锡（HASL free）, 仅对应软硬结合板外发	Sn: 2um-40um	Sn: 2um-40um
		镍钯金(ENEPIG) 外发(outward processing)	Ni: 1.0-6.0um Ba: 0.10um Au: 0.10um	Ni: 1.0-6.0um Ba: 0.10um Au: 0.10um
		镀硬金(Hard gold plating)外发(outward processing)	Ni: 1.0-6.0um Au: 0.02um-0.5um	Ni: 1.0-6.0um Au: 0.02um-0.76um
		镀软金(Soft gold plating)外发(outward processing)	Ni: 1.0-6.0um Au: 0.02um-0.1um	Ni: 1.0-6.0um Au: 0.02um-0.1um
		沉镍金(ENIG)	Ni: 120-200U " Au: 1-3U "	Ni: 120-200U " Au: 1-3U "
		沉银(Immersion silver)外发(outward processing)	Ag: 0.1-0.3um	Ag: 0.1-0.3um
		电镀锡(Tin plating)	2um-15um	2um-15um

Production Capabilities

14	PI 补强(PI stiffener)	贴合公差(Fit tolerance)	±0.3mm	±0.2mm
15	FR4补强(FR4 stiffener)	贴合公差(Fit tolerance)	±0.3mm	±0.2mm
16	胶纸类 (Adhesive tape)	贴合公差(Fit tolerance)	±0.50mm	±0.30mm
17	阻焊(Solder Mask)	阻焊厚度(Solder thickness)	≥15um	≥15um
		油墨颜色(Ink color)	白/黑/黄/绿/红/蓝(White / black / yellow / green / red / blue)	
		油不上PAD的最小距离(Oil minimum distance on PAD)	≥0.05mm	≥0.04mm
		油不露线或铜的最小距离(The minimum distance of oil from lines or copper)	≥0.05mm	≥0.04mm
		最小阻焊桥(Minimum resistance welding Bridge)	0.15mm	0.12mm
18	丝印(Screen printing)	位置公差(Position tolerance)	±0.3mm	±0.2mm
		油墨颜色(Ink color)	白/黑色(White / black)	
		最小丝印线宽(Minimum screen width)	≥0.12mm	≥0.10mm

Production Capabilities

19	模具(Tool)	精密模具公差（50万冲次以上）Tolerances for precision molds(500 thousand punching times)	0<L≤50mm ±0.05mm 50<L≤100mm ±0.075mm 100mm<L ±0.075%mm	样品外形以Laser为主，公差如下：The sample shape is Laser, the tolerance is as follows:0<L≤50mm ±0.05mm 50<L≤100mm ±0.075mm 100mm<L±0.075%mm
		快走丝模具公差（10万冲次）Tolerances for quick die(100 thousand punching times)	0<L≤50mm ±0.10mm 50<L≤100mm ±0.125mm 100mm<L ±0.125%mm	
		中走丝模具公差（20万冲次）Tolerances for medium wire die(200 thousand punching times)	0<L≤50mm ±0.075mm 50<L≤100mm ±0.10mm 100mm<L ±0.1%mm	
		木刀模蚀刻公差（5万冲次）Tolerances for wood knife dies(50 thousand punching times)	0<L≤50mm ±0.20mm 50<L≤100mm ±0.25mm 100mm<L ±0.25%mm	
		蚀刻刀模蚀刻公差（5万冲次）Tolerances for etching die(50 thousand punching times)	0<L≤50mm ±0.10mm 50<L≤100mm ±0.125mm 100mm<L ±0.125%mm	
		冲穴大小(Punch size)	≥0.5mm	任意大小

Production Capabilities

外形尺寸公差	实际产品尺寸公差范围：无辅料的情况下最严可以按A级标准；有辅料（除开FR4补强）的情况下最严按B级标准；有FR4补强的外形尺寸按C级标准	公差等级 未注尺寸	公差范围			
		A	B	C	未注公差登记选择	
		≤5	±0.03	±0.05		±0.1
		>5-15	±0.05	±0.1	±0.15	C
		>15-50	±0.08	±0.1	±0.2	
		>50-100	±0.1	±0.2	±0.3	
		>100	±0.1%	±0.2%	±0.3%	
		未注角度	±0.5°	±0.5°	±0.1°	
20	激光(Laser)	激光外形公差(outline tolerance)	公差tolerance：±0.05mm（L≤10mm）		公差tolerance：±0.05mm（L≤10mm）	
		激光内穴公差(Laser inner slot tolerance)	公差tolerance：±0.05mm		公差tolerance：±0.05mm	
21	阻抗 (Impedance)	阻抗公差(Impedance tolerance)	特性阻抗一般(Characteristic impedance)50Ω ±5Ω 差分阻抗一般(Differential impedance)100Ω ±10%Ω		特性阻抗一般(Characteristic impedance)50Ω ±5Ω 差分阻抗一般(Differential impedance)100Ω ±10%Ω	

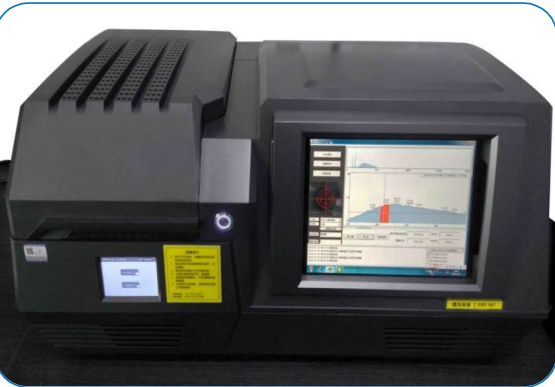
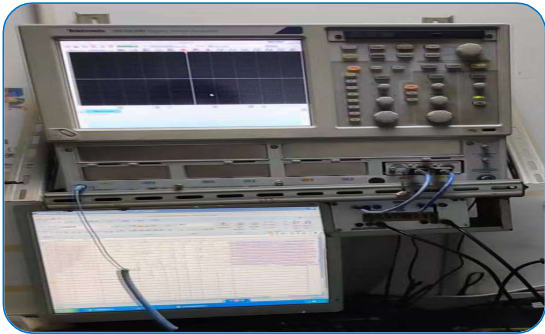
Production equipment



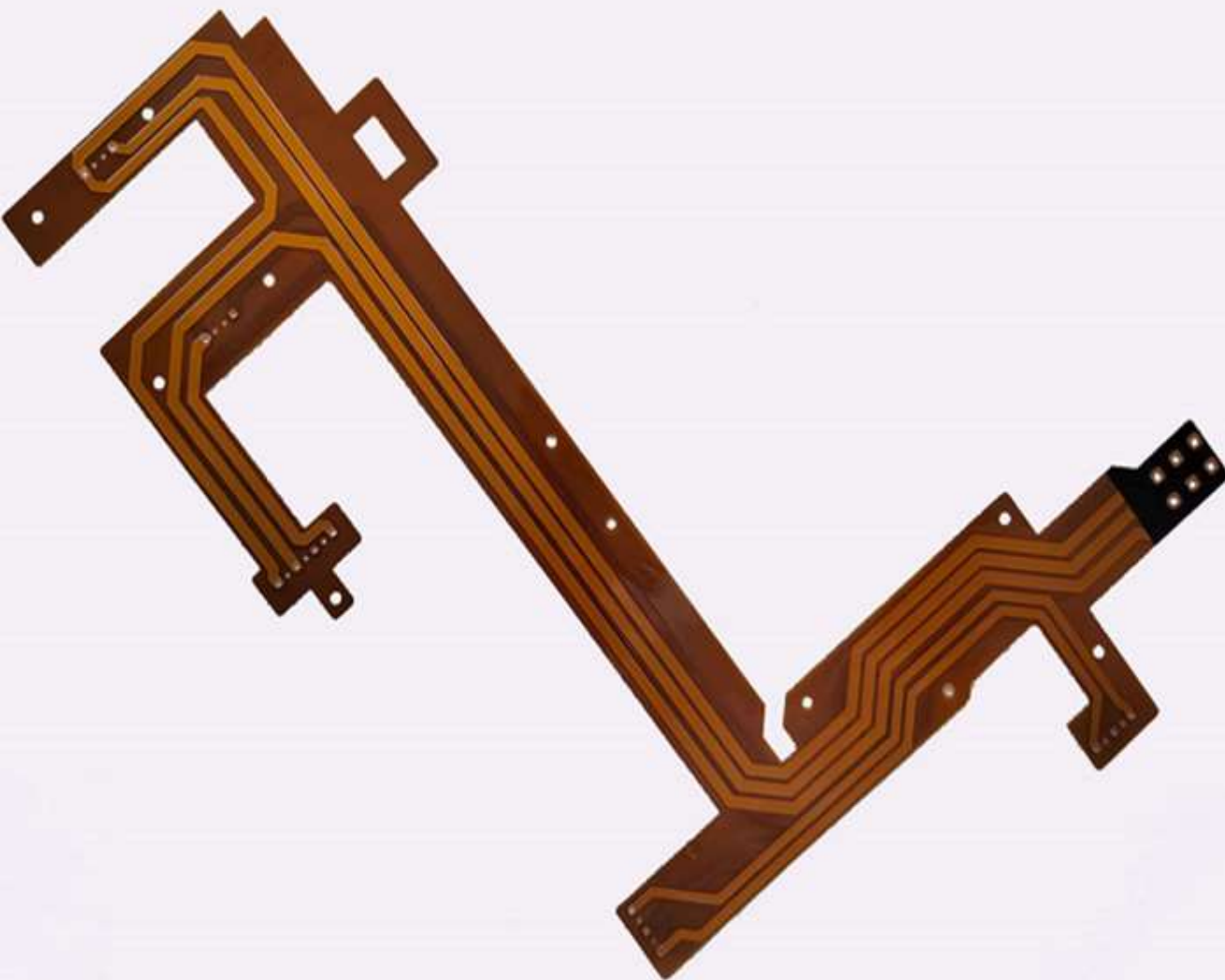
Production equipment



Production equipment



Products show



Key Specifications/Special Features

This product is mainly used in capacitive screen

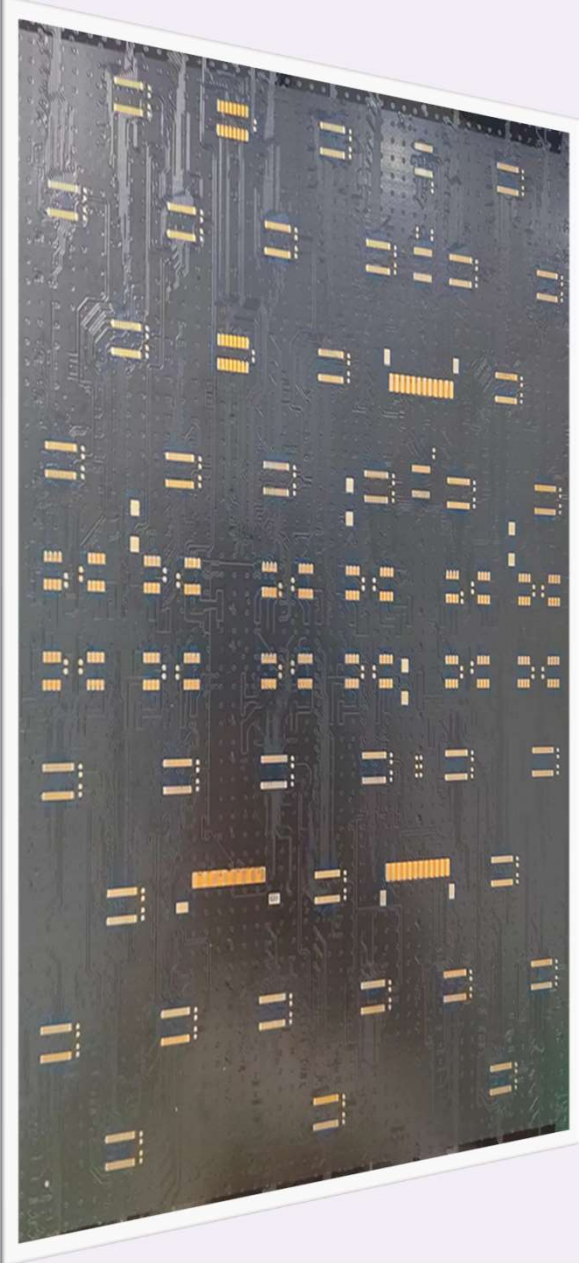
P/N#: XDYDS0001A

- No.of Layers: 2 (Customized,1-22 layers are available.)
- Copper Thickness: 2oz
- Solder mask color: Yellow
- stiffener:steel sheet(0.2mm)
- Surface Finishing:gold plating
- Board thickness: 0.35 ± 0.03 mm

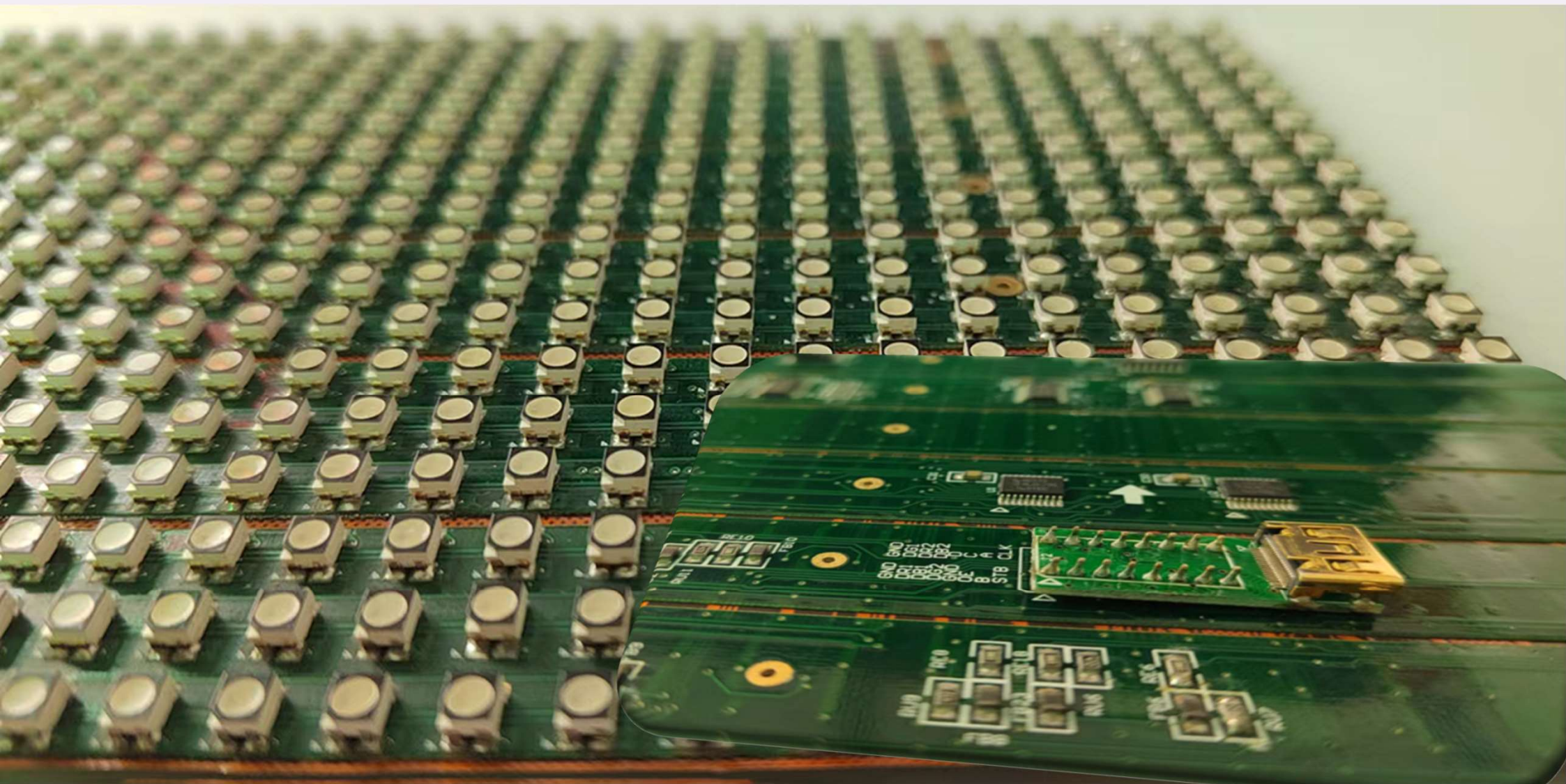
For more information,please Email us: sales@xdykj.com.cn

Customized,1-22 layers are available.

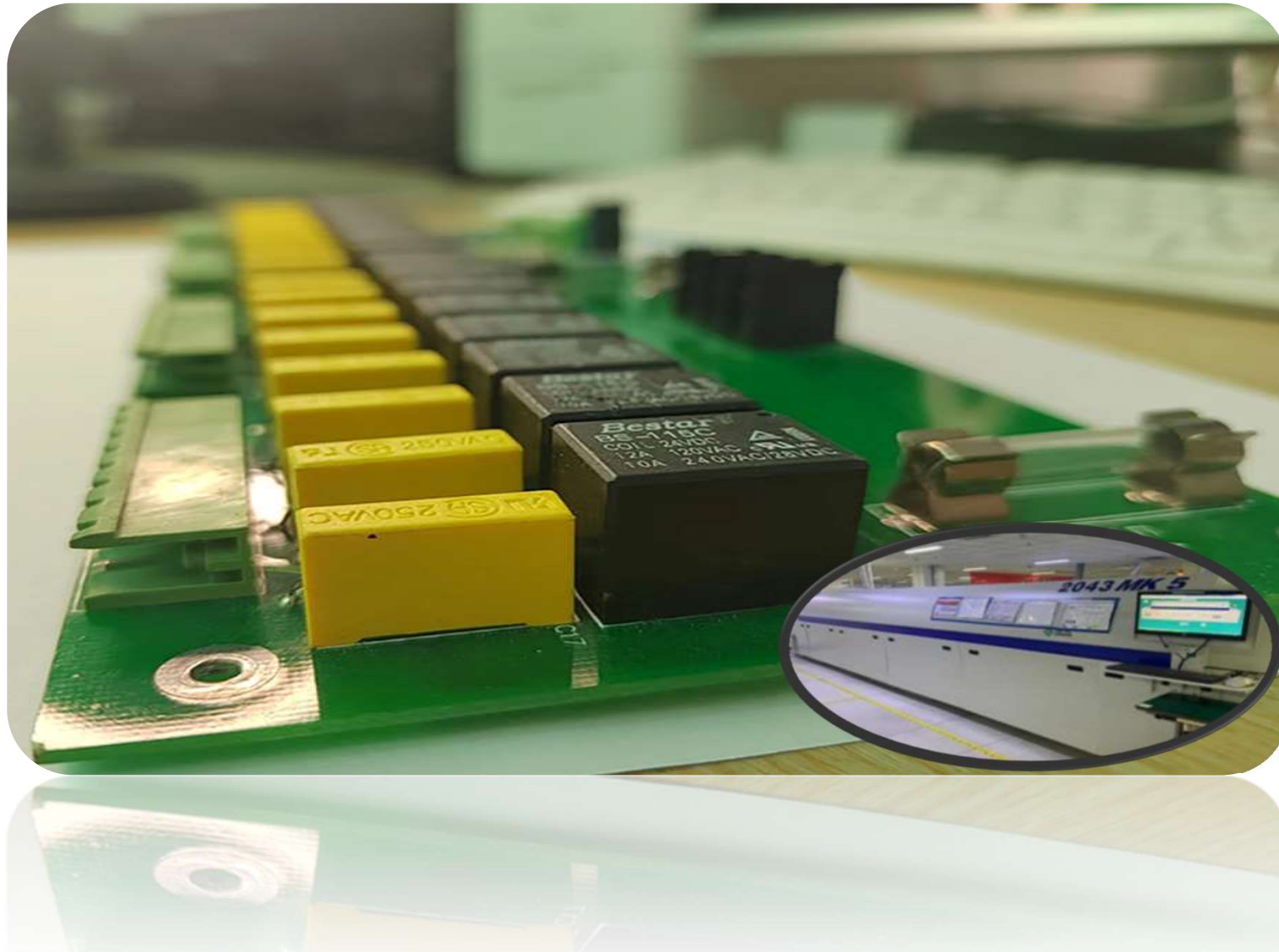
Products show



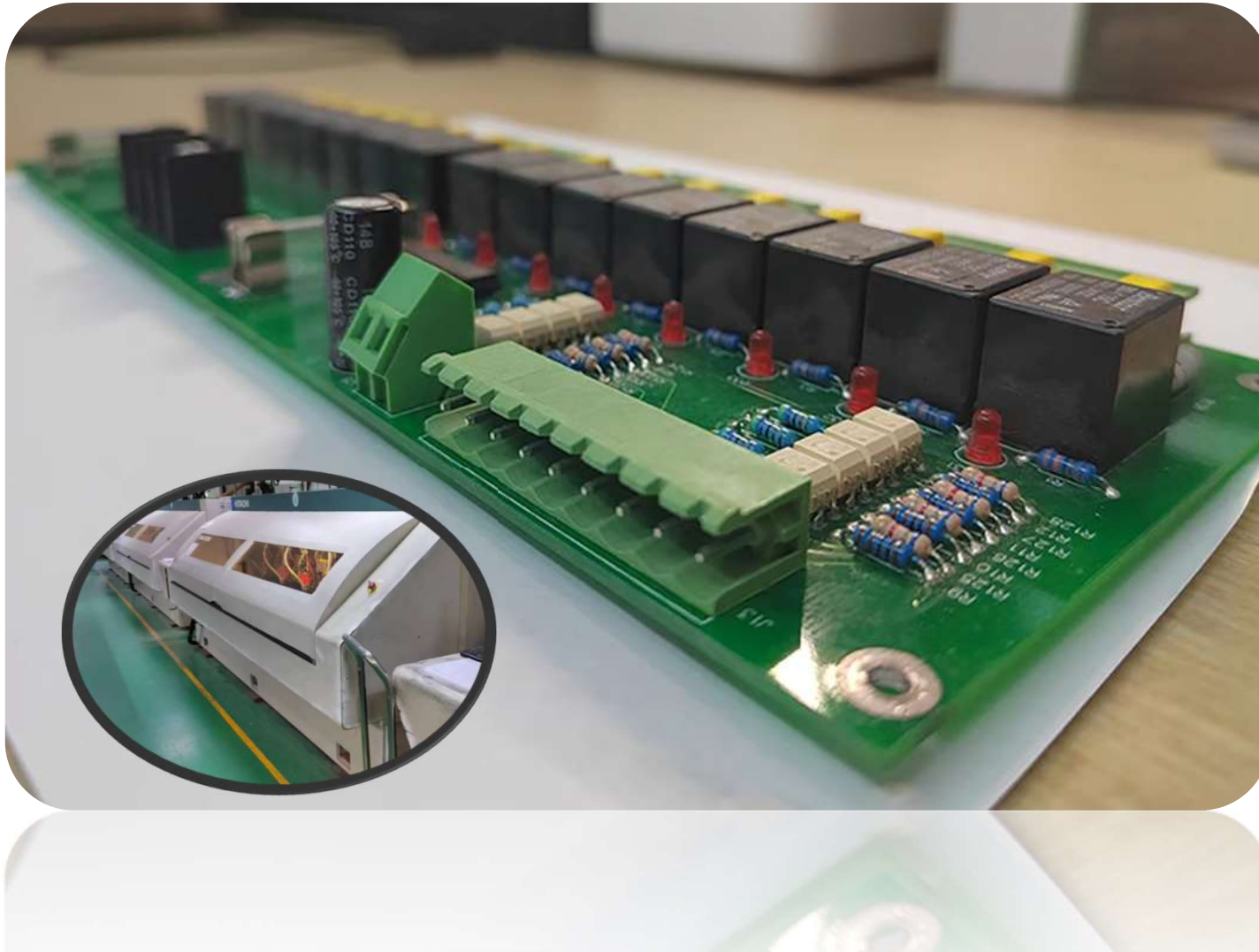
Products show



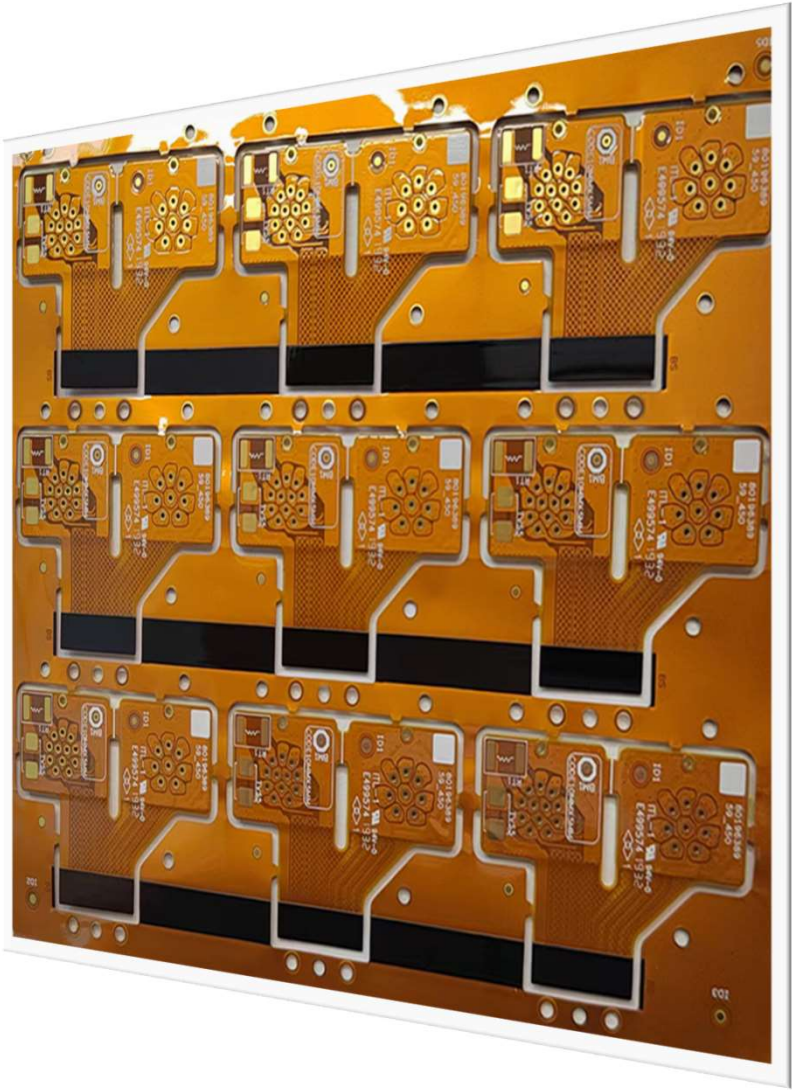
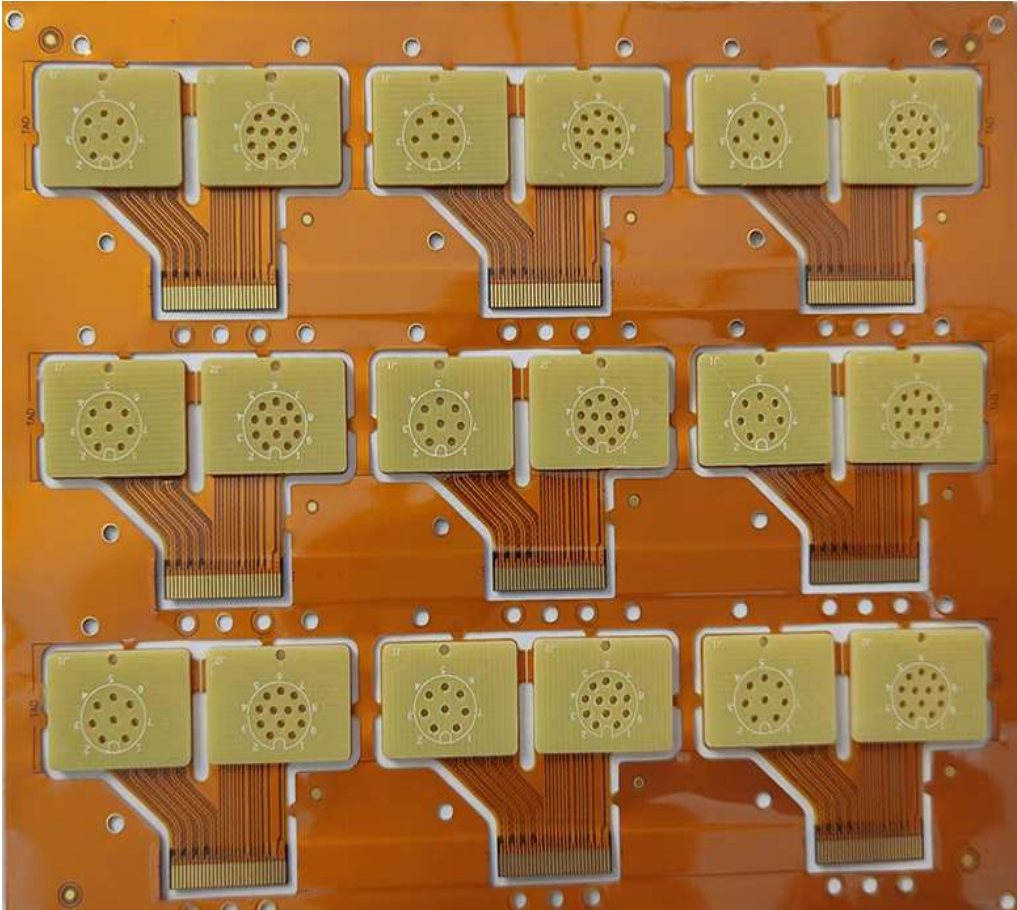
Products show



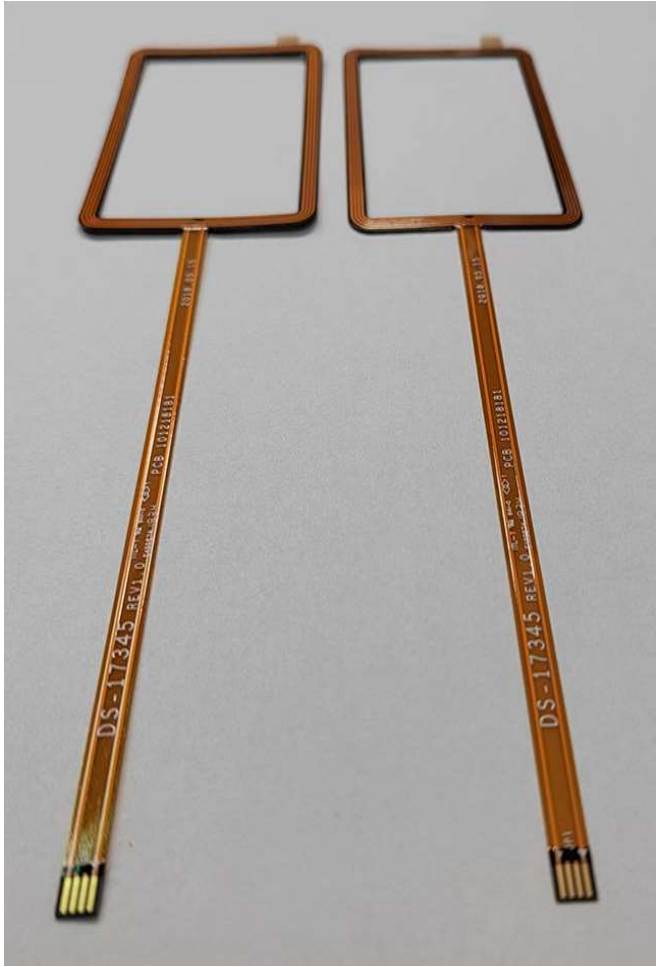
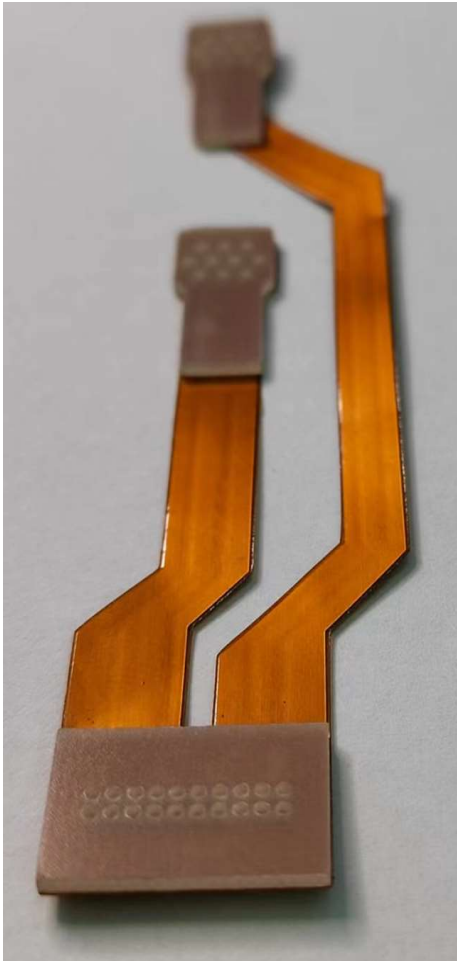
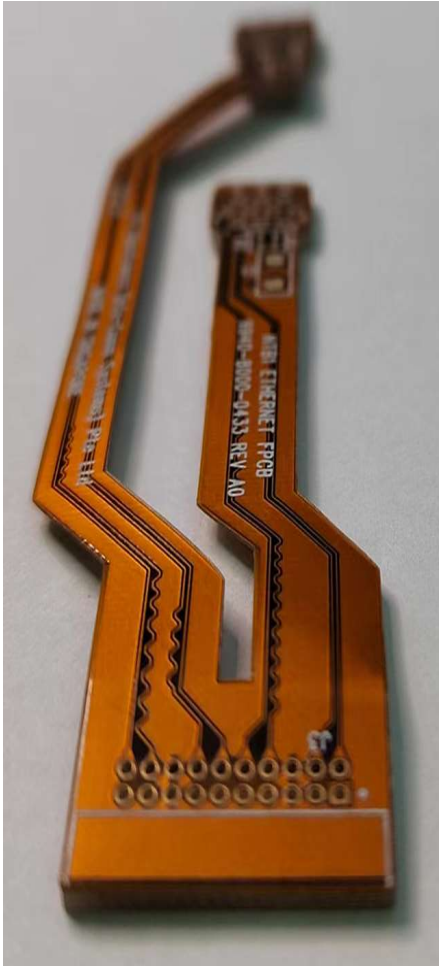
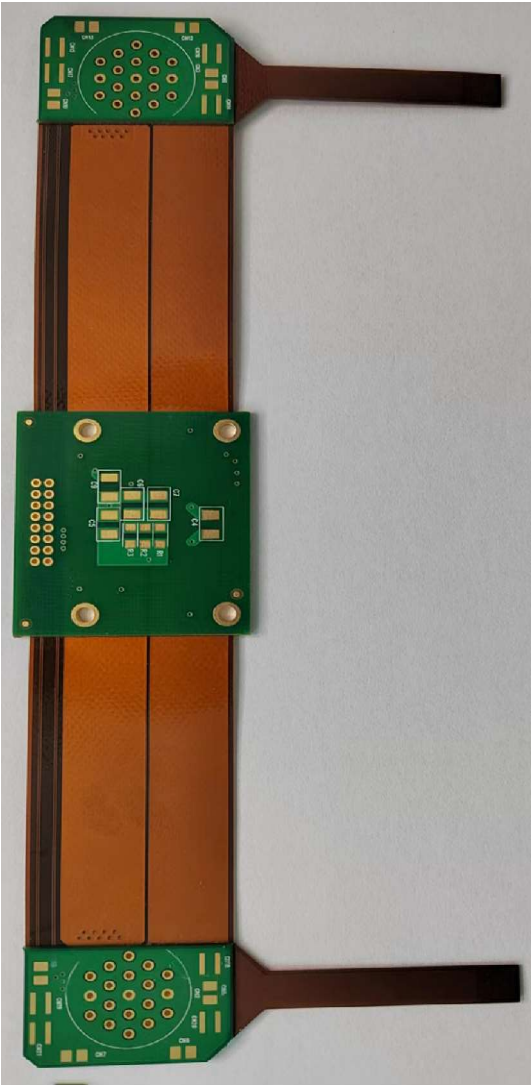
Products show



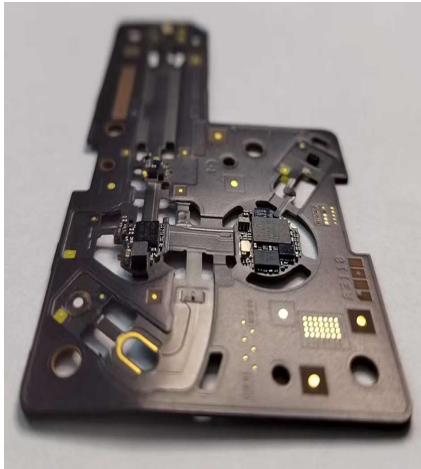
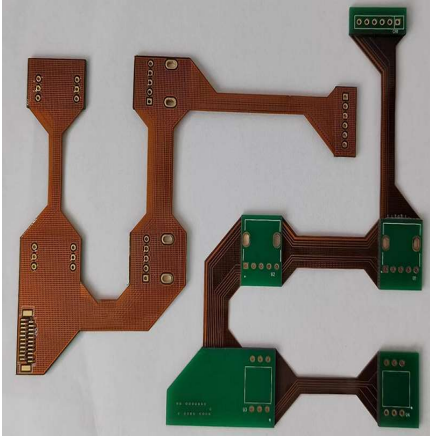
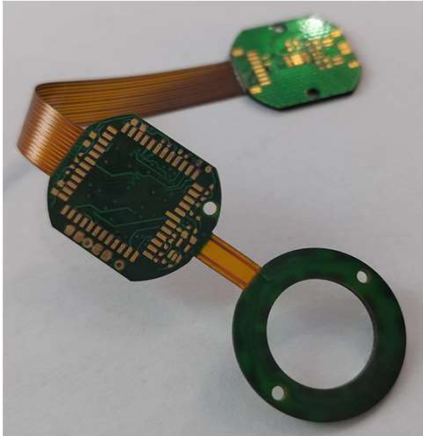
Products show



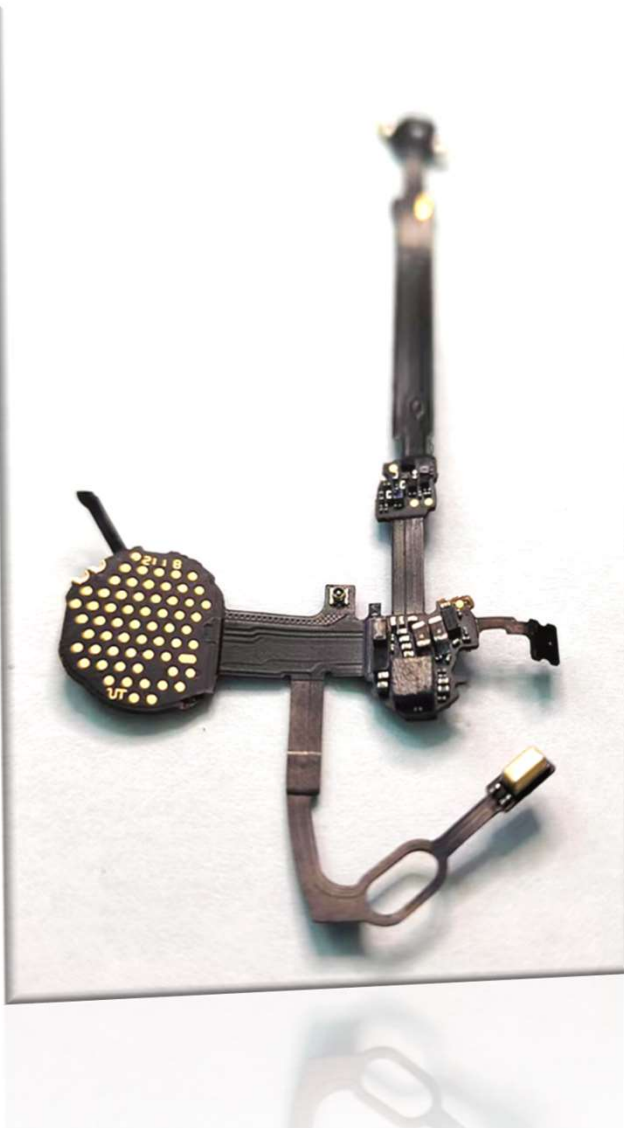
Products show



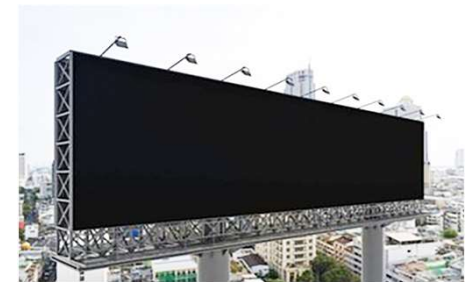
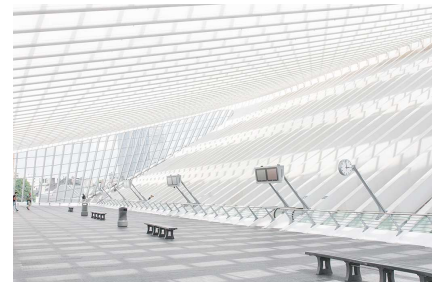
Products show

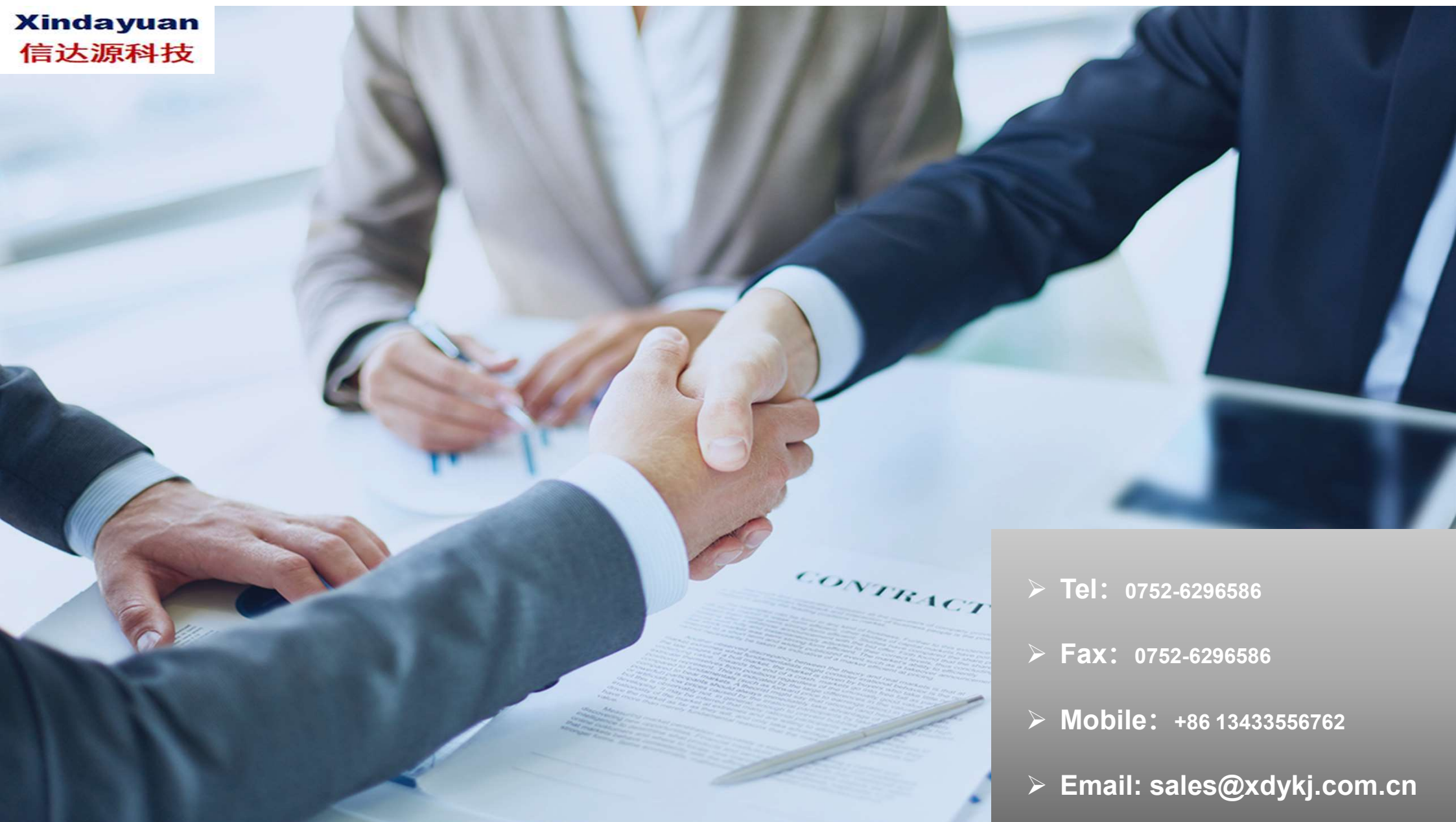


Products show



Product application field





➤ Tel: 0752-6296586

➤ Fax: 0752-6296586

➤ Mobile: +86 13433556762

➤ Email: sales@xdykj.com.cn